S/N 10/789,736 3 PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Zhiping Yin et al.

Examiner: Christian D. Wilson

Serial No.:

10/789,736

Group Art Unit: 2891

Filed:

February 27, 2004

Docket: 303.885US1

Title:

TRANSPARENT AMORPHOUS CARBON STRUCTURE IN

SEMICONDUCTOR DEVICES

COMMUNICATION CONCERNING RELATED APPLICATION(S)

Mail Stop Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Applicants would like to bring to the Examiner's attention the following related application(s) in the above-identified patent application:

Serial/Patent No.	Filing Date/Issue Date	Attorney Docket	<u>Title</u>
11/215614	August 30, 2005	303.864US2	TRANSPARENT AMORPHOUS
			CARBON STRUCTURE IN
			SEMICONDUCTOR DEVICES
11/215532	August 30, 2005	303.864US3	TRANSPARENT AMORPHOUS
11,210002	114845150, 2005	303.001003	CARBON STRUCTURE IN
			SEMICONDUCTOR DEVICES
11/215761	August 30, 2005	303.864US4	TRANSPARENT AMORPHOUS
	8		CARBON STRUCTURE IN
			SEMICONDUCTOR DEVICES
11/215671	August 30, 2005	303.869US2	MASKING STRUCTURE HAVING
11/2150/1	1148451 50, 2005	505.007052	MULTIPLE LAYERS INCLUDING AN
			AMORPHOUS CARBON LAYER
			AMORFIOUS CARBON LATER

Continuations and divisionals may be later filed on the cases listed above, or cited to the Examiner in any previous Communication Concerning Related Applications. Applicants request that the Examiner review all continuations and divisionals of the above-listed or previously-cited patent applications before allowing the claims of the present patent application.

COMMUNICATION CONCERNING RELATED APPLICATIONS

Serial Number: 10/789,736 Filing Date: February 27, 2004

Title: TRANSPARENT AMORPHOUS CARBON STRUCTURE IN SEMICONDUCTOR DEVICES

Page 2

Dkt: 303.885US1

Respectfully submitted,

ZHIPING YIN ET AL.

By Applicants' Representatives,

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Date 17 () Closer 2005

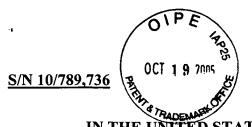
David R. Cochran

Reg. No. 46,632

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 17 day of October, 2005.

KACIA LEE

Signature



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Zhiping Yin et al. Examiner:

Christian D Wilson

Serial No.:

10/789,736

Group Art Unit:

2891

Filed:

Docket:

303.885US1

Title:

February 27, 2004 TRANSPARENT AMORPHOUS CARBON STRUCTURE IN

SEMICONDUCTOR DEVICES

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

MS Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 et. seq., the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Supplemental Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Pursuant to 37 C.F.R. §1.97(b), it is believed that no fee or statement is required with the Supplemental Information Disclosure Statement. However, if an Office Action on the merits has been mailed, the Commissioner is hereby authorized to charge the required fees to Deposit Account No. 19-0743 in order to have this Supplemental Information Disclosure Statement considered.

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Serial No :10/789,736

Filing Date: February 27, 2004

Title: TRANSPARENT AMORPHOUS CARBON STRUCTURE IN SEMICONDUCTOR DEVICES

Page 2 Dkt: 303.885US1

The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Pursuant to 37 C.F.R. 1.98(a)(2), Applicant believes that copies of cited U.S. Patents and Published Applications are no longer required to be provided to the Office. Notification of this change was provided in the United States Patent and Trademark Office OG Notices dated October 12, 2004. Thus, Applicant has not included copies of any US Patents or Published Applications cited with this submission. Should the Office require copies to be provided, Applicant respectfully requests that notice of such requirement be directed to Applicant's below-signed representative. Applicant acknowledges the requirement to submit copies of foreign patent documents and non-patent literature in accordance with 37 C.F.R. 1.98(a)(2).

Respectfully submitted,

ZHIPING YIN ET AL.

By their Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

P.O. Box 2938

Minneapolis, MN 55402

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Date / October 2005

By .

David R. Cochran

Reg. No. 46,632

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Application Number	10/789,736	
Filing Date	February 27, 2004	
First Named Inventor	Yin, Zhiping	
Group Art Unit	2891	
Examiner Name	Wilson, Christian	

Attorney Docket No: 303.885US1

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DATE CONSIDERED EXAMINER -

PTO/SB/08A(10-01)
Approved for use through 10/31/2002. OMB 651-0031
US Patent & Trademark Office: U.S. DEPARTMENT OF COMMERCE

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INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use as many sheets as necessary)	Application Number	10/789,736	
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	First Named Inventor	Yin, Zhiping	
	Group Art Unit	2891	
	Examiner Name	Wilson, Christian	
Sheet 2 of 2	Attorney Docket No: 303.885US1		

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Examiner Initials*	Cite No ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T²
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